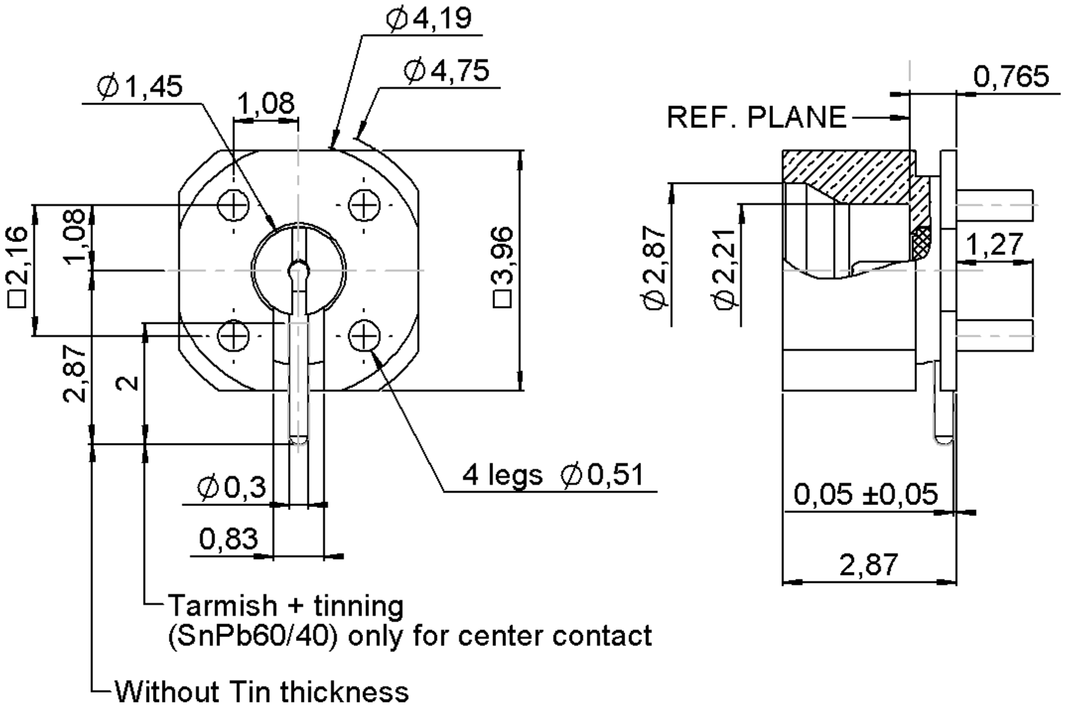
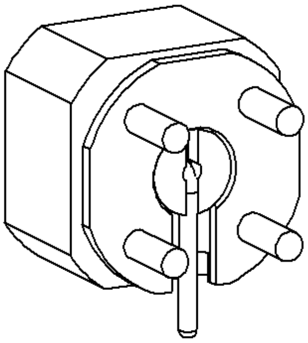
Technical Data Sheet

SOLDER SMT MALE RECEPTACLE SMOOTH BORE REEL OF 500

PAGE **1/6**	ISSUE **11-01-18A**	SERIES **SMPM**	PART NUMBER **R201428730**



Scale: 1/1



All dimensions are in mm. Tolerances according ISO 2768 m-H

COMPONENTS	MATERIALS	PLATING (µm)
Body	**BERYLLIUM COPPER**	**GOLD 0.2 OVER NICKEL 2**
Center contact	**BERYLLIUM COPPER**	**GOLD 1.3 OVER NICKEL 1.3 + TIN LEAD (60/40)**
Outer contact		
Insulator	**PEEK**	
Gasket		
Others parts		
-	-	-
-	-	-

PACKAGING

Standard	Unit	Other
500	**Contact us**	**Contact us**

ELECTRICAL CHARACTERISTICS

Impedance		**50**	Ω
Frequency		**0-20**	GHz
VSWR	** +	**0,0000**	x F(GHz) Maxi
Insertion loss		**0.12**	√F(GHz) dB Maxi
RF leakage	- (	**NA**	- F(GHz)) dB Maxi
Voltage rating		**335**	Veff Maxi
Dielectric withstanding voltage		**500**	Veff mini
Insulation resistance		**5000**	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	**6.7***	N mini
Axial force – Opposite end	**6.7***	N mini
Torque	**NA**	N.cm mini

Recommended torque		
Mating	**NA**	N.cm
Panel nut	**NA**	N.cm

Mating life	**100**	Cycles mini
Weight	**0,2400**	g

ENVIRONMENTAL

Operating temperature	**-65/+165**	°C
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

Others:

**** 1.25 to 15GHz**

**** 1.40 to 20GHz**

*****After soldering on PCB**

SOLDER PROCEDURE

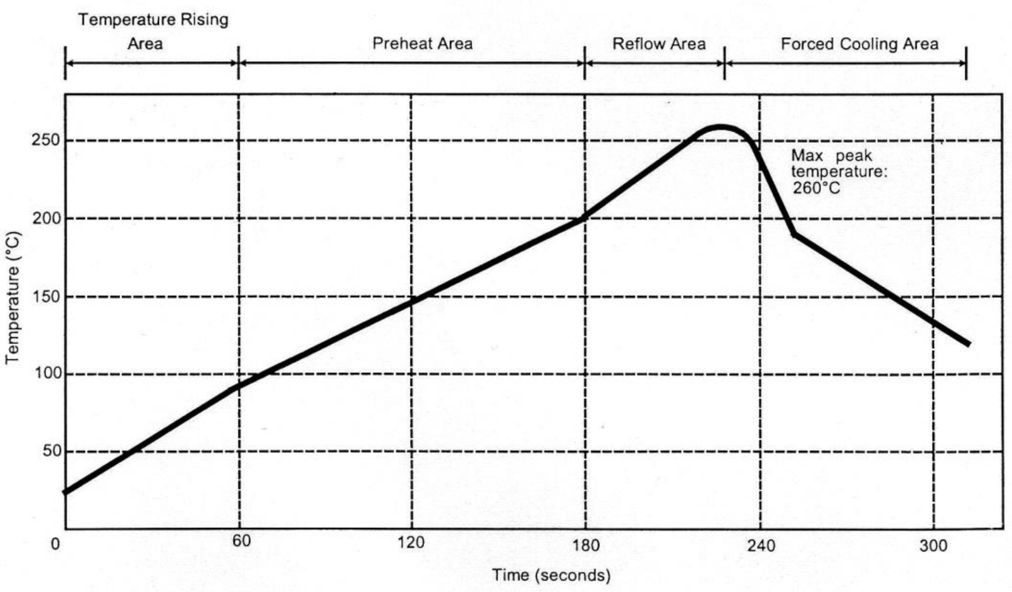
1. Deposition of solder paste ‘Sn Ag4 Cu0.5’ on mounting zone by screen printing application.
   We recommend a low residue flux.
   We advise a thickness of 150 µm. Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of ‘pick and place’ type.
   Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.

3. Soldering by infra-red reflow.
   Below, please find the typical profile to use.

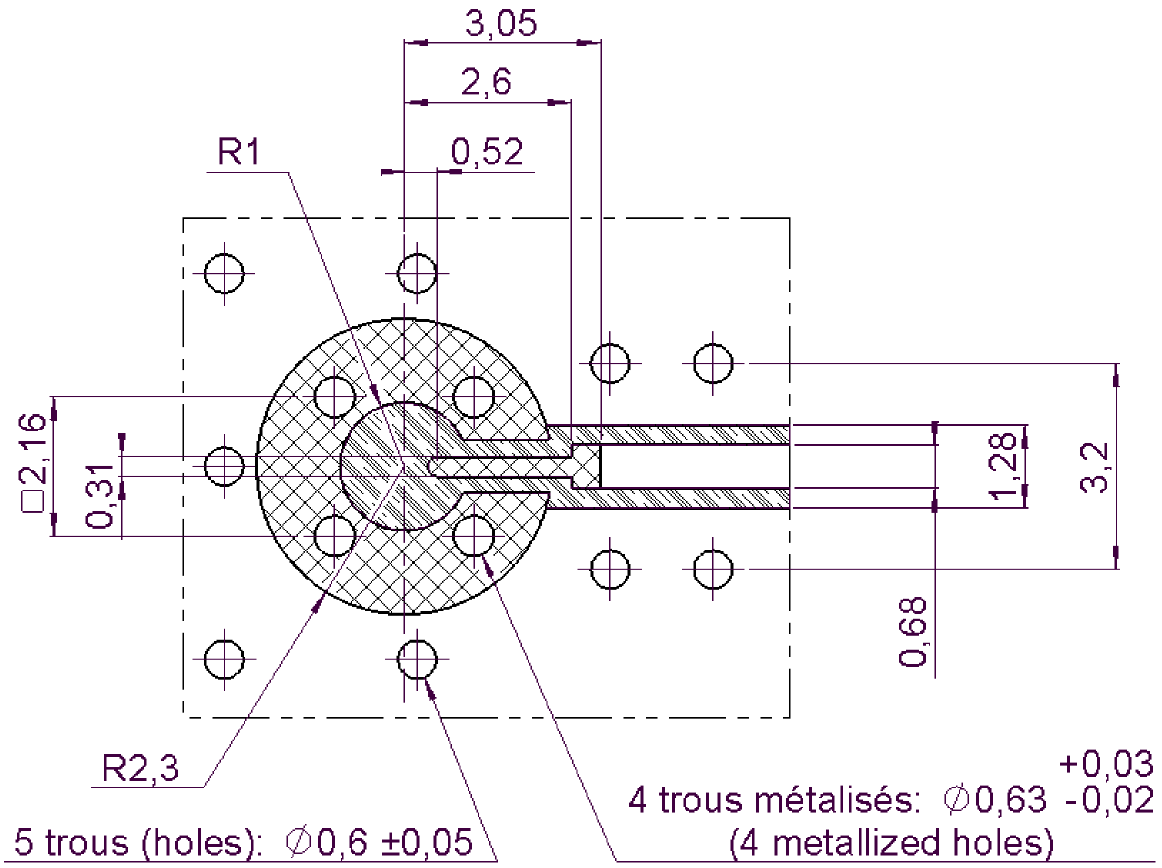
4. Cleaning of printed circuit boards.

5. Checking of solder joints and position of the component by visual inspection.



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

TOP



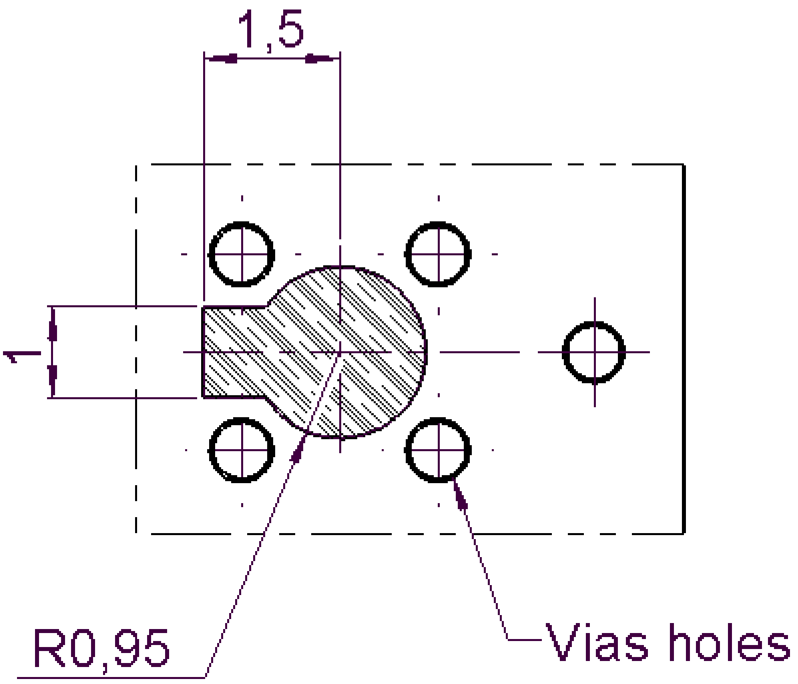
Substrat (substrate): **ROGERS RT5880**
Epaisseur (thickness): 0.254 mm
Epaisseur de cuivre (copper tickness): 35µ
Epaisseur pad de soudure:
(thickness soldering pad): 100-150µ

▨ Substrat (substrate)

☐ Cuivre (copper)

▩ Pad de soudure
(soldering pad)

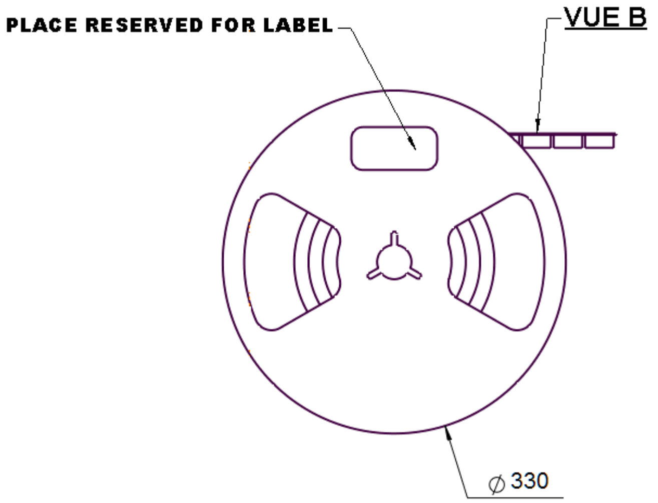
BOTTOM

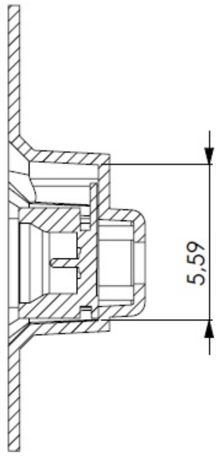


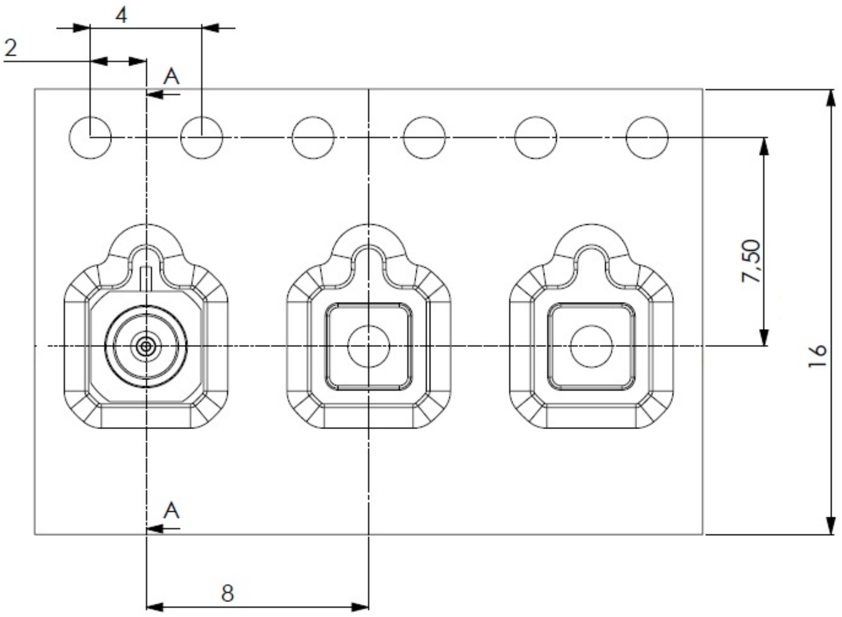
▨ Substrat (substrate)

☐ Cuivre (copper)

PACKAGING







VIEW B

AIR SUCTION